

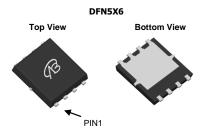
BSC040N10NS5ATMA1-VB Datasheet N-Channel 100V (D-S) MOSFET

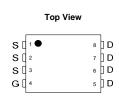
PRODUCT SUMMARY				
V _{DS} (V)	$V_{DS}(V)$ $R_{DS(on)}(\Omega)$			
100	0.003at V _{GS} = 10 V	135		
	0.004at V _{GS} = 4.5 V	120		

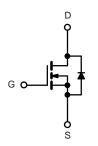
FEATURES

- 175 °C Junction Temperature
- SGT technology Power MOSFET
- Material categorization:









N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T_C =	= 25 °C, unless othe	rwise noted)			
Parameter	Symbol	Limit	Unit		
Gate-Source Voltage		V _{GS}	±20	V	
Continuous Drain Current (T _J = 175 °C) ^b	T _C = 25 °C	I-	135		
	T _C = 100 °C	l _D	80 ^a		
Pulsed Drain Current	I _{DM}	405	А		
Continuous Source Current (Diode Conduction)	I _S	140 ^a			
Avalanche Current		I _{AS}	75	1	
Single Avalanche Energy (Duty Cycle ≤ 1 %)	L = 0.1 mH	E _{AS}	110	mJ	
Mariana Pauca Dissination	T _C = 25 °C	P _D	136	W	
Maximum Power Dissipation	T _A = 25 °C	' D	3 ^b , 8.3 ^{b, c}	VV	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Manifesture Investigat to Amelianda	t ≤ 10 sec	- R _{thJA}	15	18	°C/W		
Maximum Junction-to-Ambient ^a	Steady State		40	50			
Maximum Junction-to-Case		R _{thJC}	0.85	1.1			

Notes:

- a. Package limited.
- b. Surface mounted on 1" x 1" FR4 board.
- c. $t \le 10$ s.



Parameter	Symbol	Test Conditions	Min.	Typ. ^a	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	100				
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1	2	3	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		$V_{DS} = 30V, V_{GS} = 0 V$			1		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 30V, V_{GS} = 0 V, T_{J} = 125 ^{\circ}C$			50	μΑ	
		$V_{DS} = 30V, V_{GS} = 0 V, T_{J} = 175 ^{\circ}C$		250			
On-State Drain Current ^b	I _{D(on)}	V _{DS} = 5 V, V _{GS} = 10 V	60			Α	
		V _{GS} = 10 V, I _D = 20 A		0.003			
Davis Course Co Clata Basistanah	P	V _{GS} = 10 V, I _D = 20 A, T _J = 125 °C		0.008		Ω	
Drain-Source On-State Resistance ^b	R _{DS(on)}	V _{GS} = 10 V, I _D = 20 A, T _J = 175 °C		0.010			
		V _{GS} = 4.5 V, I _D = 35 A		0.004			
Forward Transconductance ^b	9 _{fs}	V _{DS} = 15 V, I _D = 20 A		60		S	
Dynamic							
Input Capacitance	C _{iss}			7600		pF	
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = 100 \text{ V}, f = 1 \text{ MHz}$		470			
Reverse Transfer Capacitance	C _{rss}			225			
Total Gate Charge ^c	Qg			84	70		
Gate-Source Charge ^c	Q_{gs}	$V_{DS} = 100 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 50 \text{ A}$		16		nC	
Gate-Drain Charge ^c	Q _{gd}			17			
Turn-On Delay Time ^c	t _{d(on)}			20	26		
Rise Time ^c	t _r	V_{DD} = 100 V, R_L = 0.6 Ω		15	25	ns	
Turn-Off Delay Time ^c	t _{d(off)}	$I_D\cong 50$ A, V_{GEN} = 10 V, R_g = 2.5 Ω		35	50		
Fall Time ^c	t _f			20	30		
Source-Drain Diode Ratings and Cha	aracteristics (T _C = 25 °C)					
Pulsed Current	I _{SM}				405	Α	
Diode Forward Voltage	V_{SD}	I _F = 20 A, V _{GS} = 0 V		1	1.5	V	
Reverse Recovery Time	t _{rr}	I _F = 20 A, di/dt = 100 A/μs		4	135	ns	

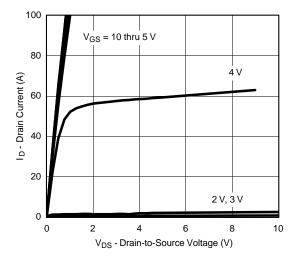
Notes:

- a. For design aid only; not subject to production testing.
- b. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- c. Independent of operating temperature.

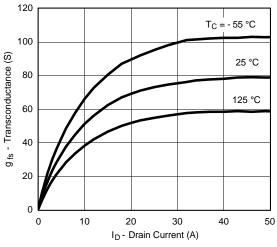
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



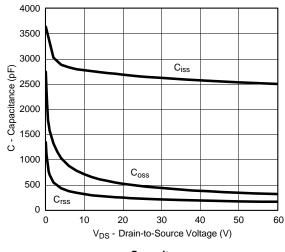
TYPICAL CHARACTERISTICS (25 °C unless noted)



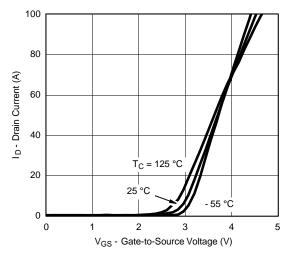
Output Characteristics



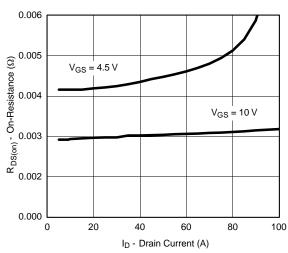
Transconductance



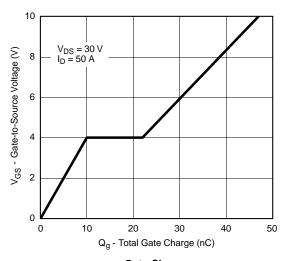
Capacitance



Transfer Characteristics



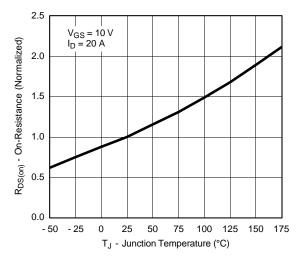
On-Resistance vs. Drain Current



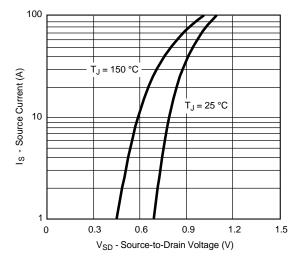
Gate Charge



TYPICAL CHARACTERISTICS (25 °C unless noted)



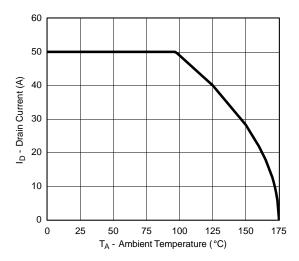
On-Resistance vs. Junction Temperature

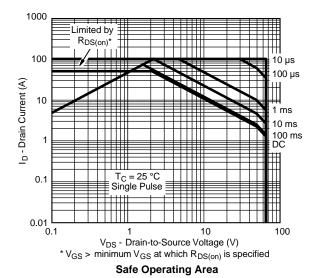


Source-Drain Diode Forward Voltage

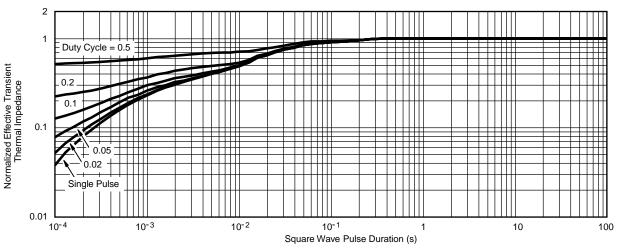


THERMAL RATINGS





Maximum Drain Current vs. Ambient Temperature



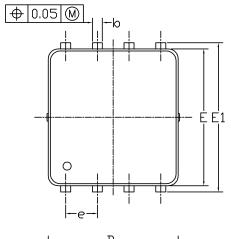
Normalized Thermal Transient Impedance, Junction-to-Case

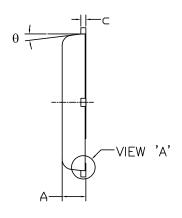
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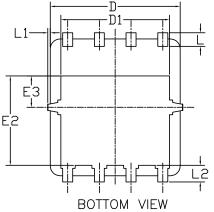
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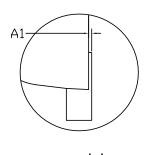


DFN5x6_8L_EP1_P PACKAGE OUTLIN



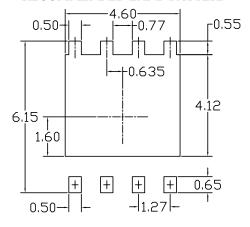






<u>VIEW 'A'</u> (SCALE 5:1)

RECOMMENDED LAND PATTERN



SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES			
3 I MIBOL3	MIN	NOM	MAX	MIN	NOM	MAX	
A	0.85	0. 95	1.00	0.033	0.037	0.039	
A1	0.00		0.05	0.000		0.002	
b	0.30	0.40	0.50	0.012	0.016	0.020	
с	0.15	0. 20	0. 25	0.006	0.008	0.010	
D	5. 10	5. 20	5. 30	0. 201	0. 205	0. 209	
D1	4. 25	4. 35	4. 45	0. 167	0.171	0. 175	
Е	5. 45	5. 55	5. 65	0.215	0.219	0. 222	
E1	5. 95	6.05	6. 15	0. 234	0. 238	0. 242	
E2	3. 525	3.625	3. 725	0.139	0.143	0. 147	
E3	1. 175	1.275	1.375	0.046	0.050	0.054	
e	1. 27 BSC			0. 050 BSC			
L	0.45	0. 55	0.65	0.018	0.022	0.026	
L1	0		0. 15	0		0.006	
L2	0.68 REF			0.027 REF			
θ	0°		10°	0°		10°	

NOTE

- 1. PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS. MOLD FLASH AT THE NON-LEAD SIDES SHOULD BE LESS THAN 6 MILS EACH.
- 2. CONTROLLING DIMENSION IS MILLIMETER. CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.

UNIT: mm



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